
AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended): A light wavelength converting module comprising:

a semiconductor laser from which a fundamental wave exits;

a light wavelength converting element which is optically coupled to the semiconductor laser, and which converts a wavelength of the fundamental wave which has entered from the semiconductor laser;

a wavelength plate disposed at a light exiting side of the light wavelength converting element; and

a removing portion, disposed between the wavelength plate and the light wavelength converting element, for removing the fundamental wave from light incident on the removing portion;

wherein the removing portion is an IR cutting filter.
2. (canceled).
3. (original): A light wavelength converting module according to claim 1, wherein the light wavelength converting element is directly joined to the semiconductor laser.
4. (original): A light wavelength converting module according to claim 1, wherein the wavelength plate is one of a half-wave plate and a quarter-wave plate, with respect to a wave whose wavelength is converted.

5. (previously presented): A light wavelength converting module according to claim 1, wherein the wavelength plate is disposed substantially orthogonal to an optical axis of light incident on the wavelength plate.

6. (original): A light wavelength converting module according to claim 1, wherein a beam splitter is provided at a light exiting side of the wavelength plate.

7. (previously presented): A light wavelength converting module according to claim 1, wherein a beam splitter and a photodiode are disposed at a light exiting side of the wavelength plate, and the beam splitter and the photodiode are shielded from scattered light.

8. (original): A light wavelength converting module according to claim 1, wherein a light attenuating portion, which attenuates light passing therethrough, is provided at a light exiting side of the light wavelength converting element.

9. (original): A light wavelength converting module according to claim 6, wherein a light attenuating portion, which attenuates light passing therethrough, is provided at a light exiting side of the wavelength converting element and at a light entering side of the beam splitter.

10. (original): A light wavelength converting module according to claim 7, wherein a light attenuating portion, which attenuates light passing therethrough, is provided at a light exiting side of the wavelength converting element and at a light entering side of the beam splitter.

11. (previously presented): A light wavelength converting module according to claim 1, further comprising:

means for controlling an amount of driving current which is applied to said semiconductor laser based on converted light emitted from a light exiting side of the wavelength plate.

12. (previously presented): A light wavelength converting module according to claim 11, wherein the amount of driving current is controlled, by said means for controlling, so that a predetermined amount of converted light is output by said light wavelength converting module.

13. (previously presented): A light wavelength converting module according to claim 7, wherein said beam splitter is arranged to direct a portion of light emitted from the light exiting side of the wavelength plate to said photodiode.

14. (previously presented): A light wavelength converting module according to claim 7, wherein said semiconductor laser has an external resonator, and the beam splitter and the photodiode are shielded from scattered light from the external resonator.

15. (previously presented): A light wavelength converting module according to claim 14, further comprising a light shield, wherein the beam splitter and the photodiode are shielded from scattered light from the external resonator by the light shield, the light shield being disposed between the external resonator and the beam splitter, and between the external resonator and the photodiode.

16. (new). The module of claim 14, wherein the external resonator is disposed on a side of the semiconductor laser opposite to that of the wavelength converting element.

17. (new). The module of claim 1, wherein the wavelength converting element has an end surface inclined at an angle in relation to a receiving surface of the IR cutting filter.